

Smart Highside Power Switch

for Industrial Applications

Features

- Overload protection
- Current limitation
- Short circuit protection
- Thermal shutdown
- Overvoltage protection (including load dump)
- Fast demagnetization of inductive loads
- Reverse battery protection¹)
- Undervoltage and overvoltage shutdown with auto-restart and hysteresis
- Open drain diagnostic output
- Open load detection in ON-state
- CMOS compatible input
- Loss of ground and loss of V_{bb} protection
- Electrostatic discharge (ESD) protection

Application

• µC compatible power switch with diagnostic feedback for 12 V and 24 V DC grounded loads in industrial applications

Product Summary Overvoltage protection

Operating voltage

On-state resistance

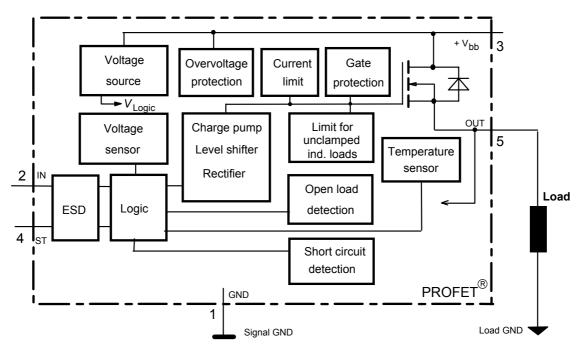
Load current (ISO)

Current limitation

- All types of resistive, inductive and capacitve loads
- Replaces electromechanical relays, fuses and discrete circuits

General Description

N channel vertical power FET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS[®] technology. Providing embedded protective functions.



¹⁾ With external current limit (e.g. resistor R_{GND}=150 Ω) in GND connection, resistors in series with IN and ST connections, reverse load current limited by connected load.

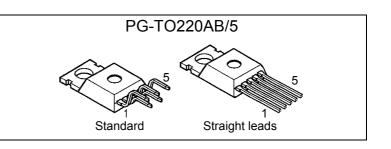
220 m Ω RON 1.8 А IL(ISO) I_{L(SCr)} 5 А Operating temperature -30...+85 °C Ta

4.7 ... 42

65

V

V



 $V_{bb(AZ)}$

Vbb(on)



Pin	Symbol		Function
1	GND	-	Logic ground
2	IN	I	Input, activates the power switch in case of logical high signal
3	Vbb	+	Positive power supply voltage, the tab is shorted to this pin
4	ST	S	Diagnostic feedback, low on failure
5	OUT (Load, L)	0	Output to the load

Maximum Ratings at $T_j = 25$ °C unless otherwise specified

Parameter	Symbol	Values	Unit
Supply voltage (overvoltage protection see page 3)	V _{bb}	65	V
Load dump protection ²) $V_{\text{LoadDump}} = U_A + V_s$, $U_A = 13.5 \text{ V}$ $R_1^{3} = 2 \Omega$, $R_L = 6.6 \Omega$, $t_d = 400 \text{ ms}$, IN= low or high	V _{Load dump} 4 ₎	100	V
Load current (Short circuit current, see page 4)	<i>I</i> L	self-limited	Α
Junction temperature	Tj	+150	°C
Operating temperature range	Ta	-30+85	
Storage temperature range	T_{stg}	-40+105	
Power dissipation (DC), $T_C \le 25 \text{ °C}$	P _{tot}	50	W
Inductive load switch-off energy dissipation, single pulse $V_{bb} = 12V$, $T_{j,start} = 150^{\circ}C$, $T_C = 150^{\circ}C$ const.		4.5	
$I_{\rm L}$ = 1.8 A, Z _L = 2.3 H, 0 Ω :	E _{AS}	4.5	J
Electrostatic discharge capability (ESD)IN:(Human Body Model)all other pins:acc. MIL-STD883D, method 3015.7 and ESD assn. std. S5.1-1993	V _{ESD}	1 2	kV
Input voltage (DC)	V _{IN}	-0.5 +6	V
Current through input pin (DC)	I _{IN}	±5.0	mA
Current through status pin (DC)	I _{ST}	±5.0	
see internal circuit diagrams page 6			

Thermal Characteristics

Parameter and Con	Symbol	Values			Unit	
		_	min	typ	max	
Thermal resistance	chip - case:	R _{thJC}			2.5	K/W
	junction - ambient (free air):	R _{thJA}			75	

²⁾ Supply voltages higher than V_{bb(AZ)} require an external current limit for the GND and status pins, e.g. with a 150 Ω resistor in the GND connection and a 15 k Ω resistor in series with the status pin. A resistor for the protection of the input is integrated. $R_{\rm I}$ = internal resistance of the load dump test pulse generator $V_{\rm Load\ dump}$ is setup without the DUT connected to the generator per ISO 7637-1 and DIN 40839

³⁾

⁴⁾



Electrical Characteristics

Parameter and Conditions	Symbol	Values			Unit
at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified		min	typ	max	
Load Switching Capabilities and Characteristics					
On-state resistance (pin 3 to 5)					
$I_{\rm L} = 1.6 \text{ A}$ $T_{\rm j} = 25 \text{ °C}:$	R _{ON}		190	220	mΩ
<i>T</i> j=150 °C:			390	440	
Nominal load current, ISO Norm (pin 3 to 5) $V_{ON} = 0.5 \text{ V}, T_{C} = 85 \text{ °C}$	I _{L(ISO)}	1.6	1.8		A
Output current (pin 5) while GND disconnected or GND pulled up, V_{bb} =30 V, V_{IN} = 0, see diagram page 7, T_{i} =-40+150°C	I _{L(GNDhigh)}			1	mA
Turn-on time IN _ to 90% V _{OUT} :	<i>t</i> on	12		125	μs
Turn-off time IN \frown to 10% V_{OUT} :	<i>t</i> off	5		85	
<i>R</i> _L = 12 Ω, <i>T</i> _j =-40+150°C					
Slew rate on	dV/dt _{on}			3	V/μs
10 to 30% V _{OUT} , R _L = 12 Ω, T _j =-40+150°C					
Slew rate off 70 to 40% V_{OUT} , R_{L} = 12 Ω , T_{j} =-40+150°C	-dV/dt _{off}			6	V/µs

Operating Parameters

Operating voltage ⁵)	<i>T</i> _j =-40+150°C:	V _{bb(on)}	4.7		42	V
Undervoltage shutdown	<i>T</i> j =25°C:	V _{bb(under)}	2.9		4.5	V
	<i>T</i> _j =-40+150°C:		2.7		4.7	
Undervoltage restart	<i>T</i> _j =-40+150°C:	V _{bb(u rst)}			4.9	V
Undervoltage restart of charge see diagram page 13	pump	V _{bb(ucp)}		5.6	6.0	V
Undervoltage hysteresis $\Delta V_{bb(under)} = V_{bb(u rst)} - V_{bb(under)}$		$\Delta V_{\rm bb(under)}$		0.1	-	V
Overvoltage shutdown	<i>T</i> j =-40+150°C:	V _{bb(over)}	42		52	V
Overvoltage restart	<i>T</i> _j =-40+150°C:	V _{bb(o rst)}	40			V
Overvoltage hysteresis	<i>T</i> _j =-40+150°C:	$\Delta V_{bb(over)}$		0.1		V
Overvoltage protection ⁶⁾	<i>T</i> _j =-40+150°C:	V _{bb(AZ)}	65	70		V
I _{bb} =4 mA	-					
Standby current (pin 3)	<i>T</i> _j =-40+25°C:	I _{bb(off)}		10	15	μA
V _{IN} =0	<i>T</i> _j = 150°C:			18	25	
Leakage output current (includ VIN=0	I _{L(off)}			20	μA	
Operating current (Pin 1) ⁷), V_{IN} $T_j = -40+150^{\circ}C$	I _{GND}		1	2.1	mA	

5)

⁵⁾ At supply voltage increase up to V_{bb}= 5.6 V typ without charge pump, V_{OUT} ≈V_{bb} - 2 V
⁶⁾ Meassured without load. See also V_{ON(CL)} in table of protection functions and circuit diagram page 7.

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Parameter and Conditions	Symbol		Values		Unit
at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified		min	typ	max	
Protection Functions ⁸)	·				
Initial peak short circuit current limit (pin 3 to 5) ⁹ , (max 450 μ s if $V_{ON} > V_{ON(SC)}$)	I _{L(SCp)}				
T _j =-40°C: T _j =25°C: T _j =+150°C:		9	 12	23	А
$T_{\rm j} = +150^{\circ}\rm C$		4		15	
Repetitive overload shutdown current limit	I _{L(SCr)}				
V_{ON} = 8 V, T_j = T_{jt} (see timing diagrams, page 12)			5		Α
Short circuit shutdown delay after input pos. slope $V_{ON} > V_{ON(SC)}$, $T_j = -40+150^{\circ}C$:	t _{d(SC)}			450	μs
min value valid only, if input "low" time exceeds 60 μs					•
Output clamp (inductive load switch off) at $V_{OUT} = V_{bb} - V_{ON(CL)}$ $I_L = 40$ mA, $T_j = -40+150$ °C:	V _{ON(CL)}	61	68	73	V
<i>I</i> _L = 1 A, <i>T</i> _j =-40+150°C:				75	
Short circuit shutdown detection voltage (pin 3 to 5)	V _{ON(SC)}		8.5		V
Thermal overload trip temperature	T _{jt}	150			°C
Thermal hysteresis	ΔT_{jt}		10		K
Reverse battery (pin 3 to 1) ¹⁰⁾	-V _{bb}			32	V

Diagnostic Characteristics

Open load detection current		I _{L (OL)}			mA
(on-condition)	<i>T</i> _j =-40150°C:		2	 150	

⁷) Add I_{ST} , if $I_{ST} > 0$, add I_{IN} , if $V_{IN} > 5.5$ V

8) Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

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⁹⁾ Short circuit current limit for max. duration of $t_{d(SC)}$ max=450 µs, prior to shutdown

 ¹⁰) Requires 150 Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Note that the power dissipation is higher compared to normal operating conditions due to the voltage drop across the intrinsic drain-source diode. The temperature protection is not active during reverse current operation! Input and Status currents have to be limited (see max. ratings page 2 and circuit page 7).



Parameter and Conditions	Symbol		Values		Unit
at T_j = 25 °C, V_{bb} = 12 V unless otherwise specified		min	typ	max	
Input and Status Feedback ¹¹⁾					
Input turn-on threshold voltage $\int T_j = -40+150^{\circ}C$:	V _{IN(T+)}	1.5		2.4	V
Input turn-off threshold voltage $\overline{\ }$ T_j =-40+150°C:	V _{IN(T-)}	1.0			V
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$		0.5		V
Off state input current (pin 2), $V_{IN} = 0.4 V$	I _{IN(off)}	1		30	μA
On state input current (pin 2), V_{IN} = 5 V	I _{IN(on)}	10	25	70	μΑ
Status invalid after positive input slope	$t_{\rm d(ST\ SC)}$			450	μs
(short circuit) $T_j=-40 \dots +150^{\circ}C$:					
Status invalid after positive input slope	t _{d(ST)}	300		1400	μs
(open load)					
Status output (open drain)					
Zener limit voltage T_j =-40+150°C, I_{ST} = +50 uA:	$V_{\rm ST(high)}$	5.0	6		V
ST low voltage $T_j = -40+150^{\circ}$ C, $I_{ST} = +1.6$ mA:	V _{ST(low)}			0.4	

¹¹⁾ If a ground resistor R_{GND} is used, add the voltage drop across this resistor.

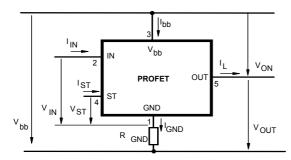


Truth Table

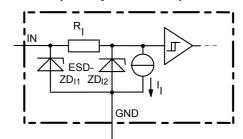
	Input-	Output	Status
	level	level	410 E2
Normal operation	L	L	Н
	н	н	н
Open load	L	¹²)	Н
-	н	Н	L
Short circuit to	L	L	Н
GND	Н	L	L
Short circuit to Vbb	L	Н	H
	Н	Н	H (L ¹³⁾)
Overtemperature	L	L	L
	Н	L	L
Undervoltage	L	L	Н
	н	L	Н
Overvoltage	L	L	Н
	Н	L	Н

L = "Low" Level X = don't care Z = high impedance, potential depends on external circuit H = "High" Level Status signal after the time delay shown in the diagrams (see fig 5. page 13)

Terms



Input circuit (ESD protection)

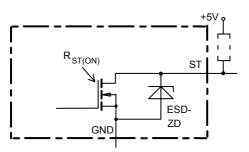


ZD_{I1} 6 V typ., ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

¹²) Power Transistor off, high impedance. ¹³) Low resistance short V_{bb} to output may be detected in ON-state by the no-load-detection



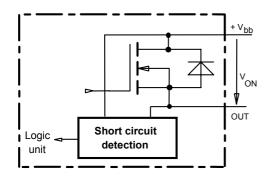
Status output



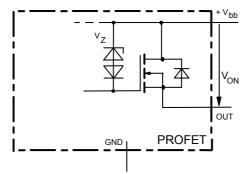
ESD-Zener diode: 6 V typ., max 5 mA; $R_{ST(ON)} < 250 \ \Omega$ at 1.6 mA, ESD zener diodes are not to be used as voltage clamp at DC conditions. Operation in this mode may result in a drift of the zener voltage (increase of up to 1 V).

Short circuit detection

Fault Condition: $V_{ON} > 8.5$ V typ.; IN high



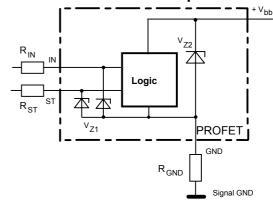
Inductive and overvoltage output clamp



VON clamped to 68 V typ.

PROFET[®] ITS 410 E2

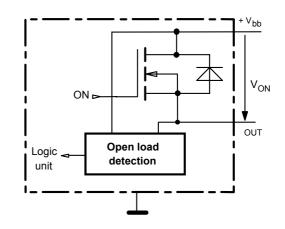
Overvolt. and reverse batt. protection



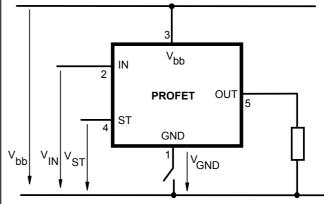
 V_{Z1} = 6.2 V typ., V_{Z2} = 70 V typ., R_{GND} = 150 Ω , R_{IN}, R_{ST} = 15 k Ω

Open-load detection

ON-state diagnostic condition: $V_{ON} < R_{ON} * I_{L(OL)}$; IN high



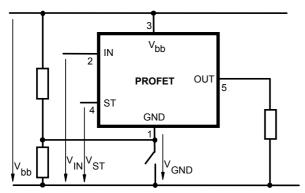
GND disconnect



Any kind of load. In case of Input=high is $V_{OUT} \approx V_{IN} - V_{IN(T+)}$. Due to V_{GND} >0, no V_{ST} = low signal available.

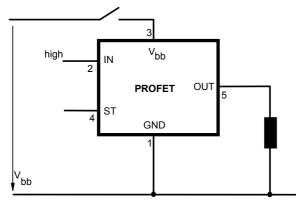


GND disconnect with GND pull up



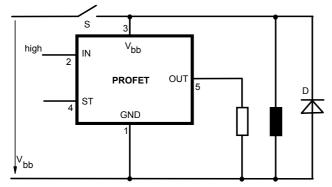
Any kind of load. If $V_{GND} > V_{IN} - V_{IN(T+)}$ device stays off Due to $V_{GND} > 0$, no V_{ST} = low signal available.

$V_{bb}\xspace$ disconnect with energized inductive load



Normal load current can be handled by the PROFET itself.

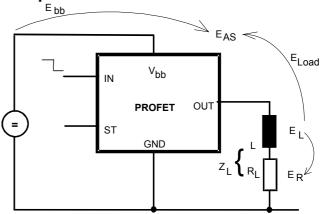
V_{bb} disconnect with charged external inductive load



If other external inductive loads L are connected to the PROFET, additional elements like D are necessary.

Inductive Load switch-off energy





Energy stored in load inductance:

$$E_{\rm L} = \frac{1}{2} \cdot L \cdot I_{\rm L}^2$$

While demagnetizing load inductance, the energy dissipated in PROFET is

$$E_{AS} = E_{bb} + E_L - E_R = \int V_{ON(CL)} \cdot i_L(t) dt$$

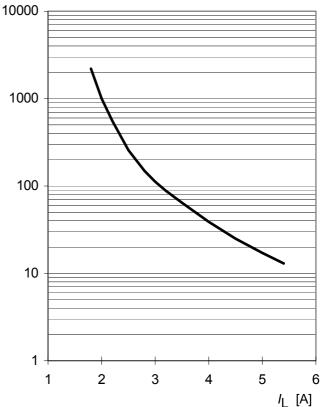
with an approximate solution for $R_L > 0 \Omega$:

$$E_{\text{AS}} = \frac{I_{\text{L}} \cdot L}{2 \cdot R_{\text{L}}} (V_{\text{bb}} + |V_{\text{OUT}(\text{CL})}|) \cdot ln (1 + \frac{I_{\text{L}} \cdot R_{\text{L}}}{|V_{\text{OUT}(\text{CL})}|})$$

Maximum allowable load inductance for a single switch off

 $L = f(I_L); T_{j,start} = 150^{\circ}C, T_C = 150^{\circ}C \text{ const.},$ $V_{bb} = 12 \text{ V}, R_L = 0 \Omega$

L [mH]





0.01

1E-5

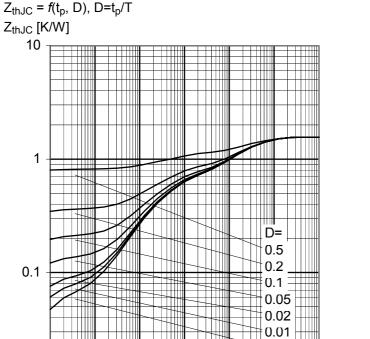
1E-4

1E-3

1E-2

1E-1

Typ. transient thermal impedance chip case



0____

1E0

1E1

*t*_p [s]



Options Overview

High-side switch, Input protection, ESD protection, load dump and reverse battery protection with 150 Ω in GND connection, protection against loss of ground

Туре	ITS410E2
Logic version	E
Overtemperature protection with hysteresis	
$T_{j} > 150 \text{ °C}, \text{ latch function}^{14}$	
T_{j} >150 °C, with auto-restart on cooling	x
Short circuit to GND protection	
switches off when V_{ON} >3.5 V typ. and V_{bb} > 7 V typ ¹⁴) (when first turned on after approx. 150 µs)	
switches off when V_{ON} >8.5 V typ. ¹⁴⁾ (when first turned on after approx. 150 µs)	X
Achieved through overtemperature protection	
Open load detection	
in OFF-state with sensing current 30 μA typ. in ON-state with sensing voltage drop across power transistor	x
Undervoltage shutdown with auto restart	X
Overvoltage shutdown with auto restart ¹⁶)	X
Status feedback for	
overtemperature	X
short circuit to GND	x
short to V _{bb}	_17)
open load	X
undervoltage	-
overvoltage	-
Status output type	
CMOS	
Open drain	X
Output negative voltage transient limit (fast inductive load switch off)	
to V _{bb} - V _{ON(CL)}	X
Load current limit	
high level (can handle loads with high inrush currents)	X
low level (better protection of application)	
Protection against loss of GND	X

¹⁴) Latch except when $V_{bb} - V_{OUT} < V_{ON(SC)}$ after shutdown. In most cases $V_{OUT} = 0$ V after shutdown ($V_{OUT} \neq 0$ V only if forced externally). So the device remains latched unless $V_{bb} < V_{ON(SC)}$ (see page 4). No latch between turn on and $t_{d(SC)}$.

¹⁵⁾ With latch function. Reseted by a) Input low, b) Undervoltage

¹⁶) No auto restart after overvoltage in case of short circuit

¹⁷) Low resistance short V_{bb} to output may be detected in ON-state by the no-load-detection



Timing diagrams

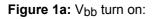
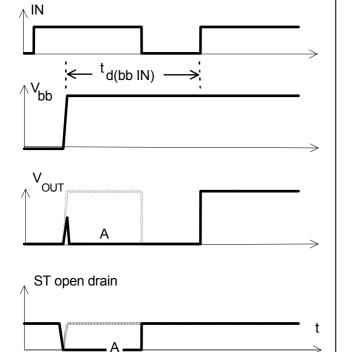
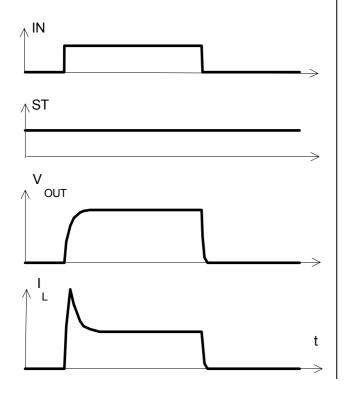


Figure 2b: Switching an inductive load

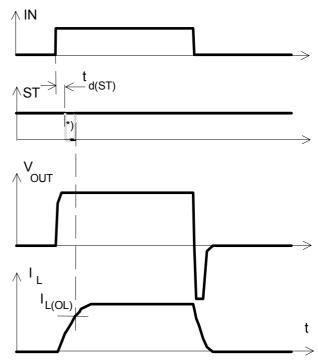


in case of too early VIN=high the device may not turn on (curve A) $t_{\rm d(bb\ IN)}$ approx. 150 $\mu \rm s$

Figure 2a: Switching a lamp,

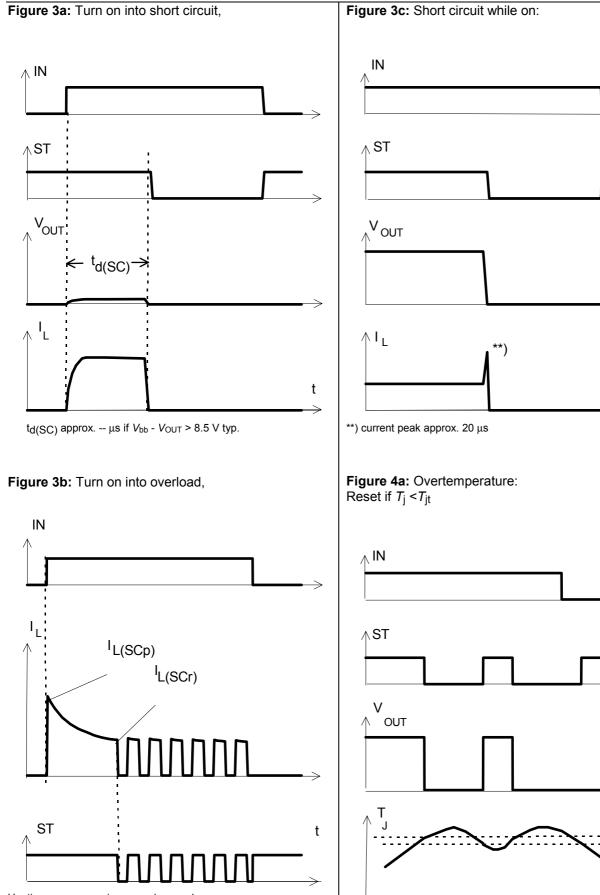


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*) if the time constant of load is too large, open-load-status may occur





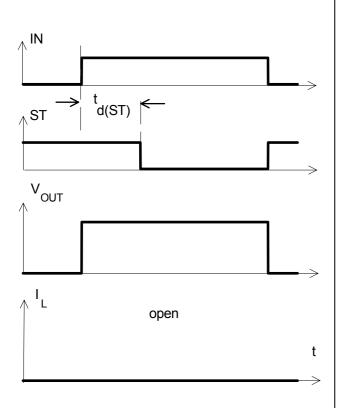
Heating up may require several seconds, $V_{\rm bb}$ - $V_{\rm OUT}$ < 8.5 V typ.

t



Figure 5a: Open load: detection in ON-state, turn on/off to open load

Figure 6a: Undervoltage:



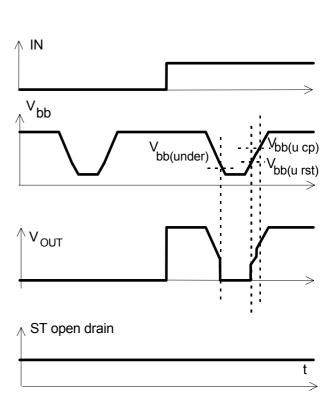
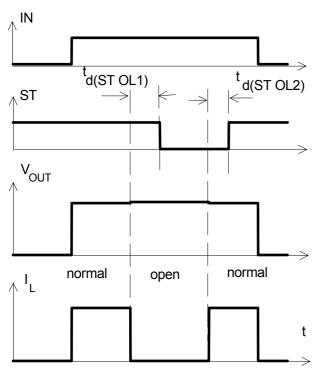
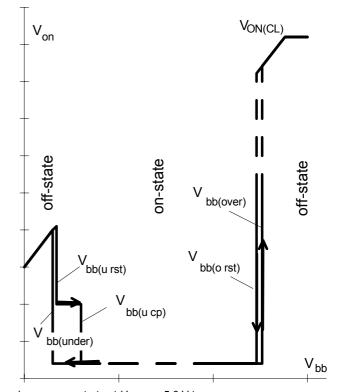


Figure 5b: Open load: detection in ON-state, open load occurs in on-state



 $t_{d(\text{ST OL1})} \text{= tbd } \mu \text{s typ., } t_{d(\text{ST OL2})} \text{= tbd } \mu \text{s typ}$

Figure 6b: Undervoltage restart of charge pump



charge pump starts at $V_{bb(ucp)}$ =5.6 V typ.

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Figure 7a: Overvoltage:

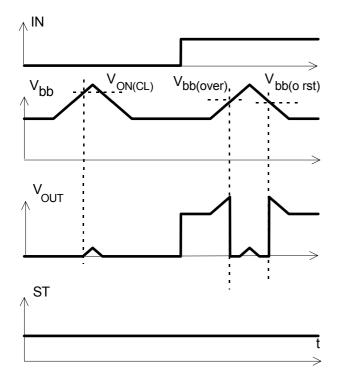
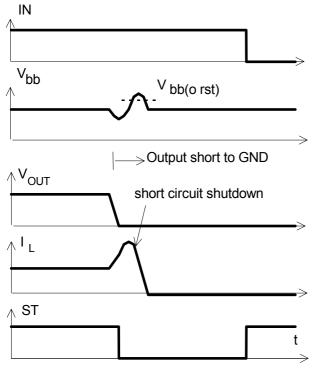


Figure 9a: Overvoltage at short circuit shutdown:



Overvoltage due to power line inductance. No overvoltage autorestart of PROFET after short circuit shutdown.

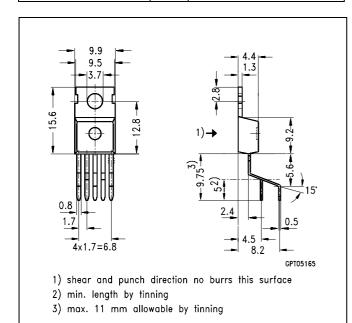


Package and Ordering Code

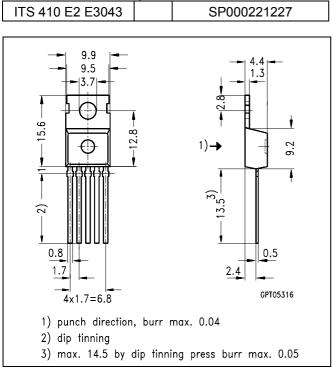
All dimensions in mm

Standard PG-TO220AB/5 Ordering code

ITS 410 E2 SP000221219



PG-TO220AB/5, Option E3043 Ordering code



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